


Full Material Declaration for attached parts list

Report generated: 21 November 2019, 10:18 GMT

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|  | Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, - |
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Declaration effective from: 1 January 2018 [Approved on 21 November 2019, 10:12 GMT]

Materials and substances

| Use/Location | Material group | % w/w of material in the part | Substances in the material | CAS Number | % w/w of substance in the material |
|-------------------|---|-------------------------------|--|------------|------------------------------------|
| Chip (die) | Other inorganic materials | 3.00000% | Gold | 7440-57-5 | 8.50000% |
| | | | ALUMINIUM | 7429-90-5 | 12.00000% |
| | | | Silicon | 7440-21-3 | 79.50000% |
| Die attach | Gold | 4.00000% | Tin | 7440-31-5 | 20.00000% |
| | | | Gold | 7440-57-5 | 80.00000% |
| Encapsulation | EP (Epoxy resin) | 68.08000% | Carbon black | 1333-86-4 | 0.30000% |
| | | | 2,2- Bis(4(2',3'-epoxypropoxy)phenyl)propane | 1675-54-3 | 0.99000% |
| | | | Epoxy resin 89 | 26335-32-0 | 27.61000% |
| | | | Quartz sand | 60676-86-0 | 71.10000% |
| Inner preparation | Gold | 0.14000% | Gold | 7440-57-5 | 100.00000% |
| Leadfinish | Tin plating | 0.68000% | Tin | 7440-31-5 | 100.00000% |
| Leadframe | Copper (e.g. copper amounts in cable harnesses) | 24.10000% | Copper | 7440-50-8 | 100.00000% |

Attached parts list

| Part number | Part name | Part Mass | Part Mass UoM |
|-----------------|----------------------|-----------|---------------|
| SOD-882/SOT-882 | Diode/Transistor SMD | 0.0001 | g |